

1                   **METHOD AND APPARATUS FOR FILLING VIAS**

2                   **ABSTRACT OF THE INVENTION**

3       **A method for filling vias, and in particular initially**  
4       **blind vias, in a wafer, and various apparatus for**  
5       **performing the method, comprising evacuating air from**  
6       **the vias; trapping at least a portion of the wafer and**  
7       **a paste for filling the vias between two surfaces; and**  
8       **pressurizing the paste to fill the vias.**